





Product Features

- Low Cost Applications
- Low Temperature Drift
- Designed for reflow soldering
- Low Magnetics
- Surface Mount Design
- Half Turn Adjustment
- Tape & Reel Packaging
- RoHS Compliant



≠ Product Applications

- NMR/ MRI Applications/Pre-Amplifiers
- **Commercial Instrumentation**
- **RFID**
- **Tunable Filter Circuits**

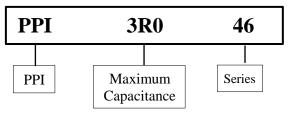


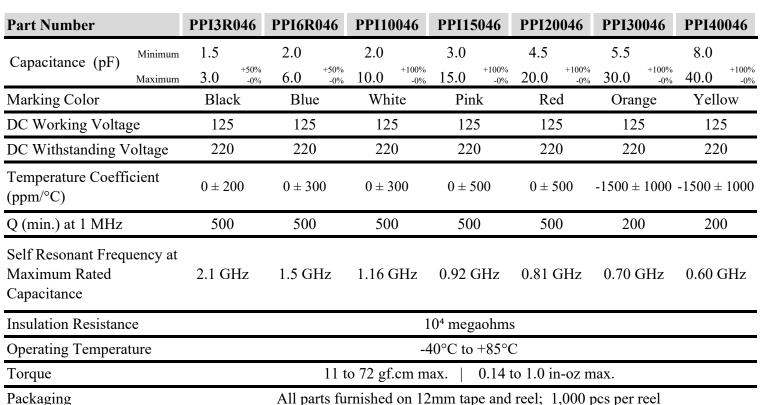
Specifications

- Capacitance Range: 1.5pF to 40pF
- DC Working Voltage: 125V
- DC Withstanding Voltage: 220V



Part Numbering





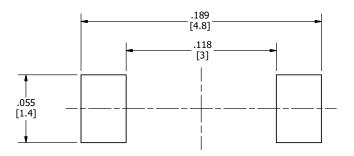






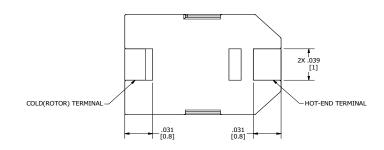


Land Pattern Dimensions (inches/mm)



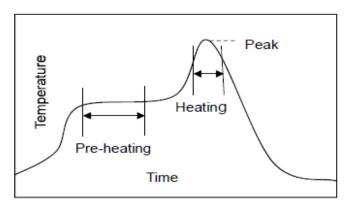
SUGGESTED FOOTPRINT SOLDER PASTE THICKNESS OF 0.15 [mm] RECOMMENDED

Dimensions (inches/mm)



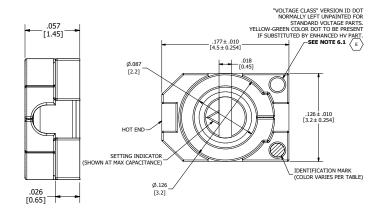


Suggested Soldering Profile



Stage	SAC305 Solder	Eutectic Solder						
Pre-Heating	Temp: 150°C - 180°C	Temp: 120°C - 150°C						
Fre-freating	Time: 60 - 120 Seconds	Time: 60 - 120 Seconds						
Heating	Temp: 220°C Min	Temp: 183°C Min						
	Time: 30 - 60 Seconds	Time: 30 - 60 Seconds						
Peak Heat	Temp: 265°C	Temp: 265°C						
	Time: 3 Seconds Max	Time: 3 Seconds Max						
Reflow Cycles	2 Times Max	2 Times Max						
Soldering Iron								
Spec	Temperature: 400°C Max							
	Time: 3 Seconds Max							

While PPI makes every effort to provide up to date and complete industry standard information, individual reflow equipment and applications vary. No guarantee is given that the suggested profile is suitable for any application or use.











Tape & Reel Specifications

Series	Measurement Unit	W	P0	P1	Т	F	Minimum Qty per Reel	Tape Material
46	in.	0.472	0.157	0.315	0.012	0.217	1000	Plastic
	mm	12.0	4.0	8.0	0.3	5.5		

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- Determined by component size. Typical clearance between the cavity and the component is: .50 (.002) min to .65 (.026) max for 12mm tape.
- The component cannot rotate more than 20° within the determined cavity.

